

REMARKS

As a result of this amendment, claims 5-13, 36-41 & 43-64 are now pending in this application.

Reservation of Rights

Applicant reserves all applicable rights not exercised in connection with this response, including, for example, the right to swear behind one or more of the cited references, the right to rebut any tacit or explicit characterization of the references, and the right to rebut any asserted motivation for combination. Applicant makes no admission regarding the prior art status of the cited references, regarding them only as being of record in the application.

Information Disclosure Statement

Applicant submitted a Supplemental Information Disclosure Statement and a 1449 Form on June 30, 2003. However, the Action neither acknowledges receipt of the Statement nor consideration of the associated references.

Accordingly, applicant requests respectfully that the Examiner acknowledge consideration by returning an initialed copy of the 1449 Form with the next official communication.

Response to Specification Objection

The Examiner objected to the Specification, specifically asserting that it omitted reference numeral 228. In response, applicant submits respectfully that the 228 is recited at page 4, line 9 of the specification. However, to reinforce clarity of the original specification, applicant amends the specification at page 8, line 20 (as shown above) to recite “to form a two-level insulative structure 228.”

Accordingly, applicant requests respectfully that the Examiner withdraw the objection.

Response to §112 Rejections

The Examiner rejected claim 7 under 35 USC §112, first paragraph. In response, applicant has amended the claim by striking the phrase “onto a least a portion of the diffusion barrier.”

Accordingly, applicant requests respectfully that the Examiner withdraw the §112 rejection of this claim.

The Examiner also rejected claims 11 and 13 under 35 USC §112, second paragraph, based on minor antecedence issues. In response, applicant has amended these claims to depend on claims 10 and 12, respectively.

Accordingly, applicant requests respectfully that the Examiner withdraw the §112 rejection of claims 11 and 13.

Response to §102 Rejections

The Examiner rejected claims 5-6, 43, 47, 54 and 57 under 35 USC §102(e) as anticipated by Mikagi (U.S. 6,153,507). In response, applicant has amended independent claims 5, 43, 47, 54, and 57 to clarify that at least a portion of the diffusion-barrier lining is on or in contact with a surface of the conductive structure that confronts a substrate.

Accordingly, applicant requests respectfully that the Examiner withdraw the §102 rejections.

Response to §103 Rejections

The Examiner rejected claim 8-13, 44-46, 48-53, 55-56 and 58-59 under 35 USC § 103(a) as unpatentable over Mikagi as applied to claims 5-6, 43, 47, 54 and 57, and further in view of Jin (Materials Research Society), Beinglass (U.S. 5,940,733), and/or Hirata (NTT System Electronics Laboratories).

In response, applicant submits respectfully that the rejection is moot with this amendment.

Conclusion

In view of the amended claims, applicant requests respectfully that the Examiner reconsider the application. Additionally, applicant request that the Examiner initiate a telephonic interview with its patent counsel, Eduardo Drake, to discuss resolution of any issues that may delay allowance of the application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743

Respectfully submitted,

KIE Y. AHN ET AL.

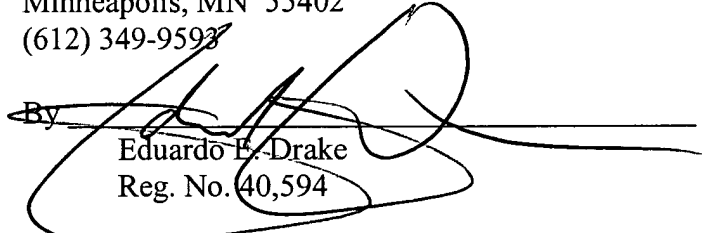
By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 349-9593

Date

12 Feb 2004

By


Eduardo F. Drake
Reg. No. 40,594

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 12 day of February, 2004.

Name

Tina Kohut

Signature

Z. L. L.